

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

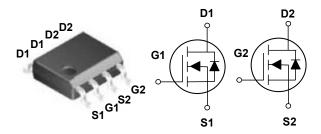
BV _{DSS}	R _{DS(ON)}	Ι _D
40 V	18 mΩ	8 A

Pb RoHS

Features

- $R_{DS(ON)} \leq 18m\Omega @V_{GS}$ =10V
- Improved dv/dt Capability
- Fast Switching
- Green Device Available

SOP-8 Pin Configuration



Applications

- Motor Drive
- Power Tools
- LED Lighting

Absolute Maxim	bsolute Maximum Ratings T _c =25°C unless otherwise noted						
Symbol	Parameter	Rating	Units				
V _{DS}	Drain-Source Voltage	40	V				
V _{GS}	Gate-Source Voltage	±20	V				
I _D	Drain Current - Continuous (T _A =25°C)	8	А				
I _{DM}	Drain Current - Pulsed (NOTE 1)	32	А				
EAS	Single Pulse Avalanche Energy (NOTE 2)	4.9	mJ				
IAS	Single Pulse Avalanche Current (NOTE 2)	9.9	А				
P _D	Power Dissipation (T _A =25°C)	2	W				
TJ	Operating Junction Temperature Range	-50 to 150	°C				
T _{STG}	Storage Temperature Range	-50 to 150	°C				
Marking Code		ND018 , DS4810					

Thermal Characteristics				
Symbol	Parameter	Тур.	Max.	Unit
$R_{ extsf{ heta}JA}$	Thermal Resistance Junction to Ambient		62.5	°C/W





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics						
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	40			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =32V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =8A			18	mΩ
		V _{GS} =4.5V , I _D =4A			25	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, I _D =250uA	1.2		2.5	V
gfs	Forward Transconductance	V _{DS} =10V , I _D =1A		5		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Qg	Total Gate Charge			10.8		
Q_gs	Gate-Source Charge	V_{DS} =32V , V_{GS} =10V , I_{D} =3A		1.6		nC
Q_{gd}	Gate-Drain Charge			3.3		
$T_{d(on)}$	Turn-On Delay Time			3.8		
Tr	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω ,		10.5		nS
$T_{d(off)}$	Turn-Off Delay Time	I _D =1A		22.2		115
T _f	Fall Time			6.6		
C_{iss}	Input Capacitance			724		
C _{oss}	Output Capacitance	V_{DS} =25V , V_{GS} =0V , F=1MHz		70		pF
C_{rss}	Reverse Transfer Capacitance			109		
R _g	Gate Resistance	V_{GS} =0V , V_{DS} =0V , F=1MHz		2.6		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current	$V_{G}=V_{D}=0V$, Force Current			8	А
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A			1	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.

2. V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS}=9.9A, R_G=25 Ω , Starting T_J=25°C.

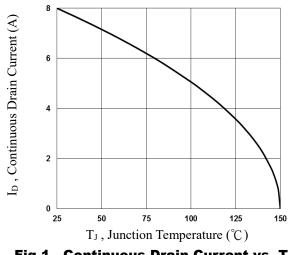
3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.

4. Essentially independent of operating temperature.



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Characteristics Curves





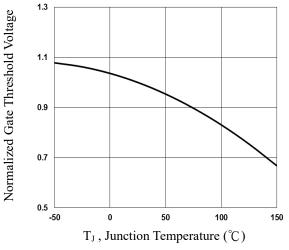
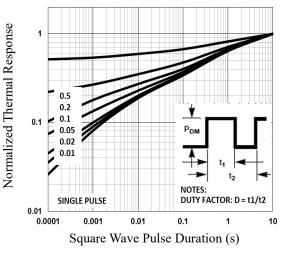


Fig.3 Normalized V_{th} vs. T_J





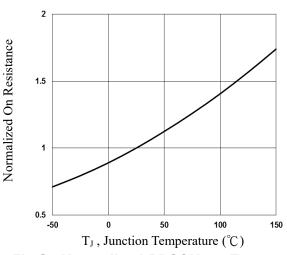


Fig.2 Normalized RDSON vs. T_J

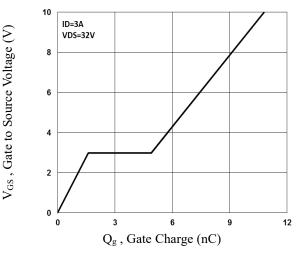
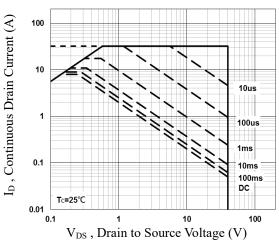


Fig.4 Gate Charge Waveform





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40V Dual N-Channel MOSFETs

Characteristics Curves

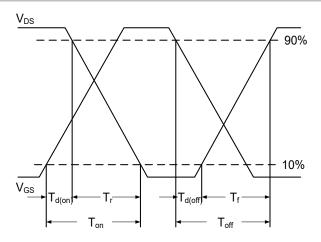
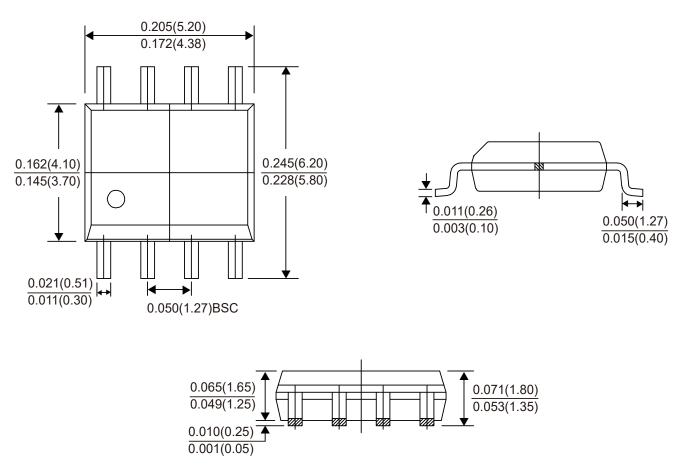


Fig.7 Switching Time Waveform

Package Outline Dimensions



SOP-8 Dimensions in inches and (millimeters)



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